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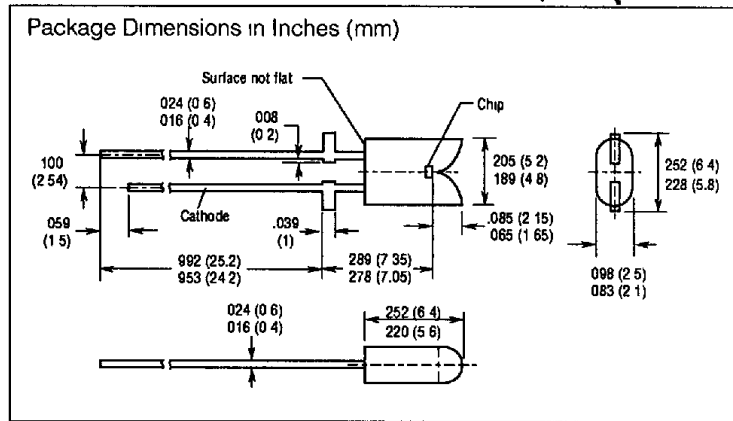
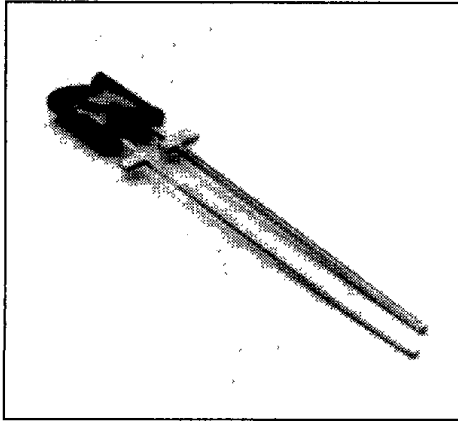
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SIEMENS**SFH 435****GaAs INFRARED EMITTER
DOUBLE EMITTING DIODE****FEATURES**

- **Package:** Special Case, Grey Tinted Epoxy Resin, Solder Tabs, 2.54 mm (1/16") Lead Spacing
- **Cathode Marking:** Short Solder Tab
- **High Reliability**
- **Long Life**
- **Diametrical Radiation**
- **High Pulse Handling Capability**
- **Good Spectral Matching with Silicon Photodetectors**

DESCRIPTION

The SFH 435 is a two-beam GaAs infrared emitting diode with one chip. The beams emerge diametrically from the diode in a half angle of 8 degrees.

The radiation is emitted in the near infrared range. It is excited by a current flowing in forward direction, dc as well as pulse operation with simultaneous modulation are possible

The SFH 435 is especially suitable for application in dual photo interrupters, i.e., light reflection switches, tape end control

Maximum Ratings

| | |
|--|-----------------|
| Reverse Voltage (V_R) | 6 V |
| Forward Current (I_F) | 100 mA |
| Surge Current (I_{FS} ($t_F \leq 10 \mu s$)) | 3 A |
| Junction Temperature (T_J) | 100°C |
| Storage Temperature Range (T_{STG}) | -55°C to +100°C |
| Soldering Temperature at Dip Soldering (≥ 2 mm distance from case bottom) ($t \leq 5$ sec) (T_S) | 260°C |
| Soldering Temperature at Iron Soldering (≥ 2 mm distance from case bottom) ($t \leq 3$ sec) (T_S) | 300°C |
| Total Power Dissipation (P_{TOT}) $T_{amb} \leq 25^\circ C$ | 165 mW |
| Thermal Resistance (R_{THA}) | 450 K/W |

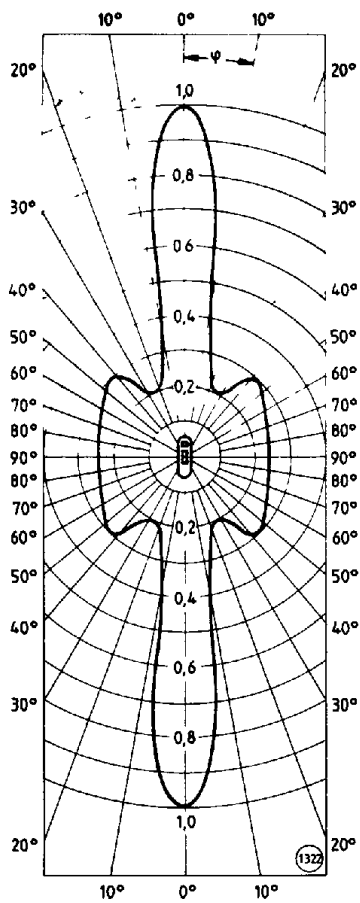
Characteristics ($T_{amb} = 25^\circ C$)

| Parameter | Symbol | Unit |
|---|------------------|-----------------|
| Wavelength at Peak Emission ($I_F = 100$ mA, $t_F = 20$ ms, $t_{OFF} = 180$ ms) | λ_{PEAK} | nm |
| Spectral Bandwidth at 50% of I_{REL} ($I_F = 100$ mA, $t_F = 20$ ms) | $\Delta\lambda$ | nm |
| Half Angle per Major Lobe | ϕ | Deg |
| Active Chip Area | A | mm ² |
| Dimensions of Active Chip Area | L x W | mm ² |
| Switching Times (I_F from 10% to 90%, $I_F = 100$ mA) | t_R, t_F | μs |
| Capacitance ($V_R = 0$ V) | C_0 | pF |
| Forward Voltage ($I_F = 100$ mA) | V_F | V |
| ($I_F = 1$ A, $t_F = 100 \mu s$) | V_F | V |
| Breakdown Voltage ($I_R = 100 \mu A$) | V_{BR} | V |
| Reverse Current ($V_R = 5$ V) | I_R | μA |
| Temperature Coefficient of I_F or ϕ_E | T_C | %/K |
| Temperature Coefficient of V_F | T_C | mV/K |
| Temperature Coefficient of λ_{PEAK} | T_C | nm/K |
| Radiant Intensity in Axial Direction at a Steradian $\Omega \geq 0.01$ sr or 6.5 degrees (measured in direction of major lobes) | | |
| ($I_F = 100$ mA, $t_F = 20$ ms) | I_E | mW/sr |
| ($I_F = 1$ A, $t_F = 100 \mu s$) | I_E | mW/sr |
| Radiant Flux, Total ($I_F = 100$ mA, $t_F = 20$ ms) | ϕ_E | mW |

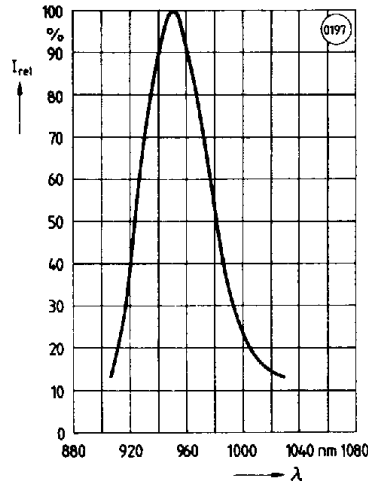
Infrared
Emitters

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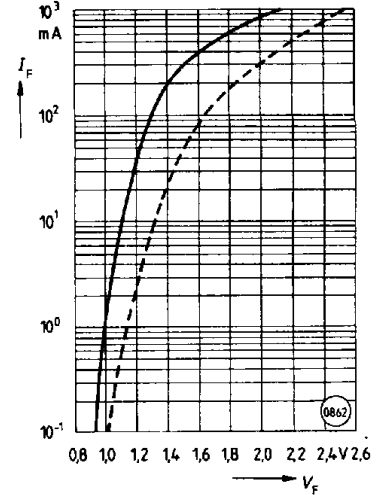
Radiation characteristic
Relative spectral emission
versus half angle



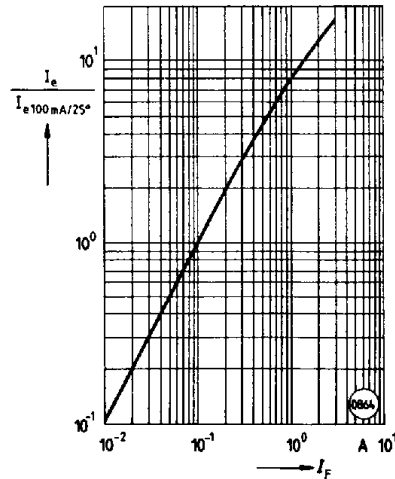
Relative spectral emission
versus wavelength



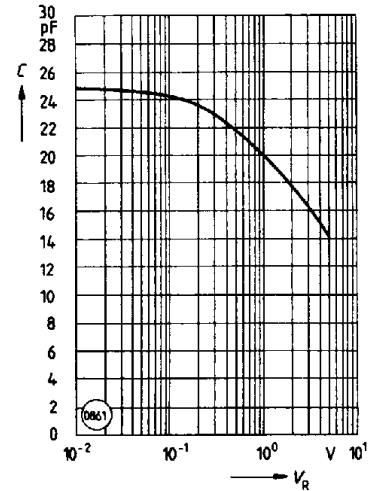
Forward current versus
forward voltage



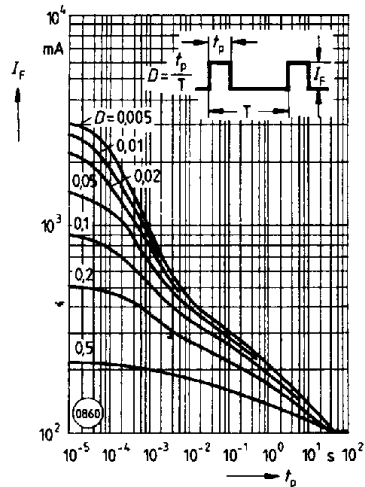
Radiant intensity versus
forward current
pulse width 5 μs, pulse spacing 6 ms



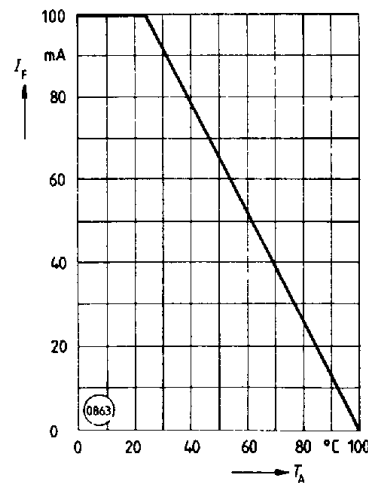
Capacitance versus reverse voltage



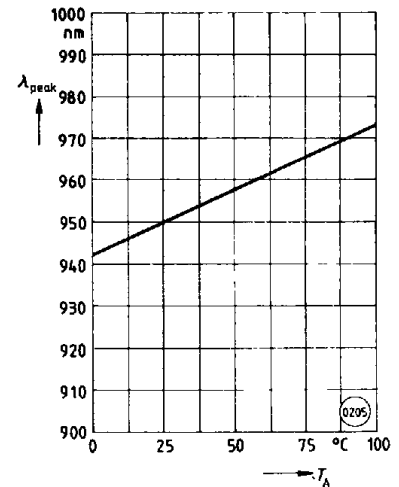
Permissible pulse handling capability
Forward current versus pulse width
Duty cycle D = parameter



Maximum permissible forward current
versus ambient temperature

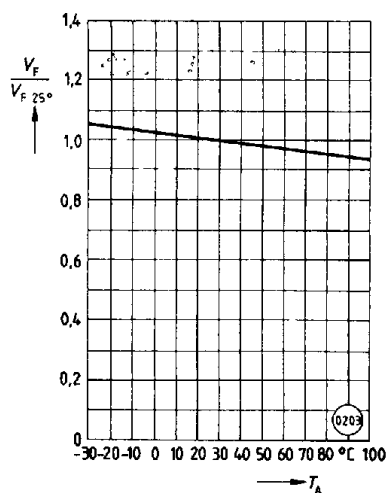


Wavelength at peak emission
versus ambient temperature

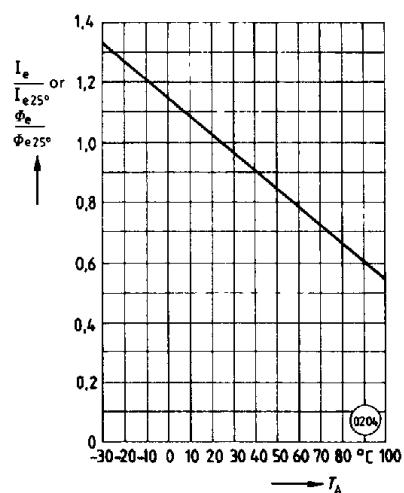


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Forward voltage versus ambient temperature



Radiant intensity versus ambient temperature



Infrared
Emitters